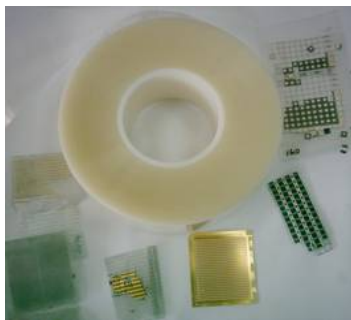


# UV Dicing Tape

**PanTech UV tape**, also called as **UV off tape** is an adhesive tape specially designed for dicing of **wafer, LED module, QFN, glass IC chips, and package sawing singulations**. It sustains a strong adhesion and turns to very low adhesion after UV exposure. This tape can hold the chips firmly during dicing, and chips can be picked up or peeled off easily after UV exposure.

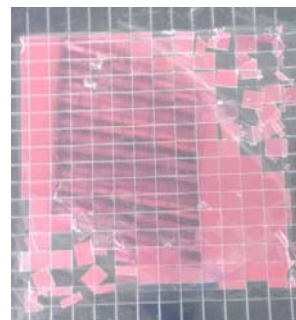
These are all **RoHS** and **halogen free**.



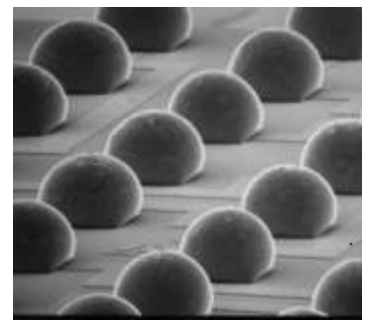
PCB Dicing Tape



Wafer Dicing Tape



Glass Dicing Tape



Gold/Solder Bumper Back Grinding Tape

## Categories:

Usage/ base film	Adhesion	140μPE	140μPO	80μPO	140μPO	80μPO	80μPO	100μPET
QFN Dicing	Ultra high	UP153	UP163 UP163-40 UP183		UB163			UV1005 UV1007
PCB Dicing	Strong	UP150	UP164					
Glass Dicing	Strong		UP163-20 UP151A	UP821 UP822	UB163-20			
Ceramic Dicing	Medium		UP1608 UP1808					
Bumper IC	Medium low						UB265 Ultra thick	
Wafer Dicing	low			UP802A		UB805 UE802		
Dicing depth		Deep	Deep	Shallow	Deep	Shallow	Back Grinding	-
Expandable/recovery		No	No	No	Yes	Yes	Yes	No
color		transparent	matt	matt	matt	matt	matt	Clear
Advantage		see through soft, conformable	clean removal	clean removal	Expandable	Expandable	ultra thick adhesive for bumper IC back grinding	excellent Temp. R.
Disadvantage		Bad Temp. Resistance						Use in dark room